

VLSI-SoC 2025

October 12-15, 2025
Puerto Varas, Chile



VLSI-SoC 2025 is the 33rd in a series of international conferences sponsored by IFIP TC 10 WG 10.5, IEEE CASS, IEEE CEDA and ACM SIGDA, which explores the state-of-the-art in the areas that surround Very Large Scale Integration (VLSI) and System-on-Chip (SoC). Previous conferences have taken place in Edinburgh, Trondheim, Tokyo, Vancouver, Munich, Grenoble, Gramado, Lisbon, Montpellier, Darmstadt, Perth, Nice, Atlanta, Rhodes, Florianópolis, Madrid, Hong Kong, Santa Cruz, Istanbul, Playa del Carmen, Daejeon, Tallinn, Abu Dhabi, Verona, Cuzco, Salt Lake City, Singapore, Patras, Sharjah, and Tangerang. The 2025 edition will take place at Puerto Varas, a tourist and top destination in South Chile, to who likes the beautiful of nature. It is a scenic location close to mountains, lakes, forests and national parks.



Paper Submission: Papers should present original research and industrial results not published or submitted for publication in other forums. Electronic submission in PDF format to the <http://www.vlsi-soc.com> website is required. The proceedings will be published by IEEE and available through IEEE Xplore.

A selection of the conference best papers will be invited to be submitted to a special issue of the ACM Journal on Emerging Technologies in Computing Systems. Also, some conference best papers will be invited to submit an extended version to be included as chapters of a book to be published by Springer.

Paper Format: Papers should not exceed 4 pages + a 5th page with only refernces (single-spaced, 2 columns, 10pt font). Submissions should be in camera-ready, following the IEEE proceedings specifications (link available at the conference webpage)

Paper Publication and Presenter Registration: Papers will be accepted for regular or poster presentation at the conference. Every accepted paper **MUST** have at least one author registered at the conference by the time the camera-ready paper is submitted; the author is also expected to attend the conference and present the paper. A limited number of travel grants are available to needy PhD students. Please see the web site for more information.

Topics of interest include but are not limited to:

- Analog and Mixed-Signal IC Design
- 3-D Integration
- Physical Design
- Electronic Design Automation
- Variability, Reliability, Fault Tolerance and Test
- Digital Signal Processing and Image Processing SoC Design
- Prototyping, Validation, Verification, Modelling, and Simulation
- Embedded Systems and Processors, Hardware/Software Codesign
- Processor Architectures and Multicore SOCs
- Logic and High-Level Synthesis
- Low-Power and Thermal-aware Design
- Reconfigurable SoC Systems for Energy and Reliability
- Green Computing Systems
- Circuits and Systems for Micro-sensing Applications

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